

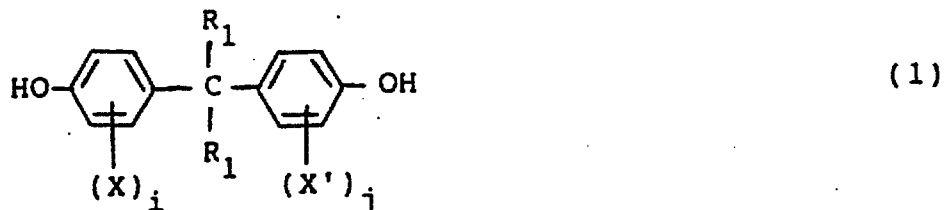
ABSTRACT

EPOXY RESIN COMPOSITION AND COPPER-CLAD LAMINATE

An epoxy resin composition excellent in heat resistance and low in dielectric and a copper-clad laminate obtained by molding it are disclosed.

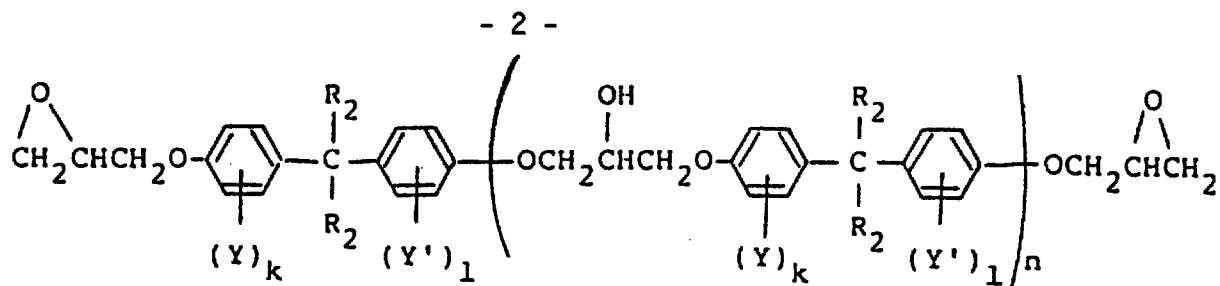
The epoxy resin composition of the invention comprises:

(1) a compound obtainable by previously reacting (A) an epoxy resin obtainable by glycidyl etherifying a 3-methyl-6-(C₁-C₈)alkylphenol novolak with (B) a halogen-containing bisphenol compound represented by the following formula (1):



wherein R₁ represents a hydrogen atom or a methyl group and the two R₁ may be identical or different, X and X' represent halogen atom and may be identical or different, and i and j independently of one another are integers of 1 to 4, or a compound obtainable by previously reacting (A) the above epoxy resin, (B) the above halogen-containing bisphenol compound and (C) a glycidyl etherification product of a halogen-containing bisphenol compound which is represented by the following formula (2):

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(2)

wherein R_2 represents a hydrogen atom or a methyl group and the two R_2 may be identical or different, Y and Y' represent halogen atom and may be identical or different, n represents an average recurring unit number and is 0 to 10 and k and l independently of one another are integers of 1 to 4, and

(2) an epoxy hardener.

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